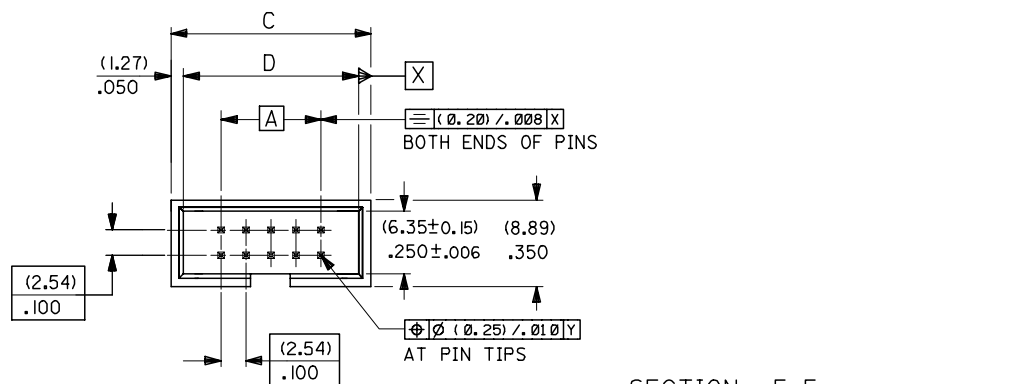
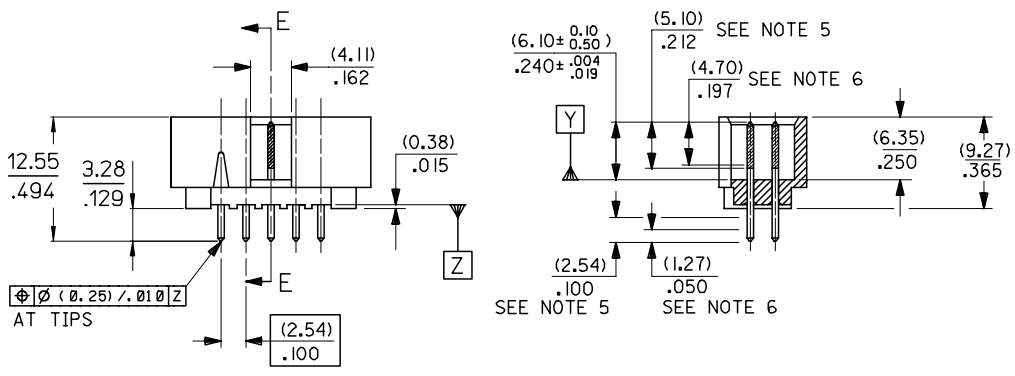


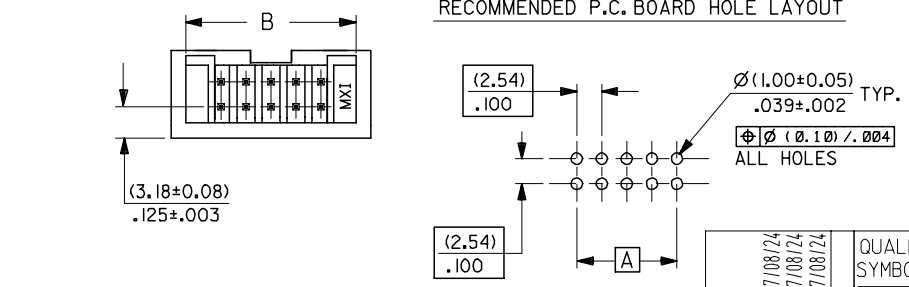
10 9 8 7 6 5 4 3 2 1



SECTION E-E



RECOMMENDED P.C. BOARD HOLE LAYOUT



| PART NUMBER | CIRCUIT SIZE | DIM A | DIM B | DIM C | DIM D |
|-------------|--------------|------------------|------------------|------------------|------------------|
| 90708-100* | 10 | (10.16) 0.400 | (17.27) 0.680 | (20.32) 0.800 | (17.78) 0.700 |
| 90708-140* | 14 | (15.24) 0.600 | (22.35) 0.880 | (25.40) 1.000 | (22.86) 0.900 |
| 90708-160* | 16 | (17.78) 0.700 | (24.89) 0.980 | (27.94) 1.100 | (25.40) 1.000 |
| 90708-200* | 20 | (22.86) 0.900 | (29.97) 1.180 | (33.02) 1.300 | (30.48) 1.200 |
| 90708-260* | 26 | (30.48) 1.200 | (37.59) 1.480 | (40.64) 1.600 | (38.10) 1.500 |
| 90708-300* | 30 | (35.56) 1.400 | (42.67) 1.680 | (45.72) 1.800 | (43.18) 1.700 |
| 90708-340* | 34 | (40.64) 1.600 | (47.75) 1.880 | (50.80) 2.000 | (48.26) 1.900 |
| 90708-400* | 40 | (48.26) 1.900 | (55.37) 2.180 | (58.42) 2.300 | (55.88) 2.200 |
| 90708-500* | 50 | (60.96) 2.400 | (68.07) 2.680 | (71.12) 2.800 | (68.58) 2.700 |
| 90708-600* | 60 | (73.66) 2.900 | (80.77) 3.180 | (83.82) 3.300 | (81.28) 3.200 |
| 90708-640* | 64 | (78.74) 3.100 | (85.85) 3.380 | (88.90) 3.500 | (86.36) 3.400 |

NOTES:

- MATERIALS: WAFER; 15% GLASS FILLED PBT, 94V-0, PINS; (0.635)/.025 SQ BRASS WIRE.
- PIN SOLDERABILITY PER MOLEX SPEC. ES-152
- PIN PUSHOUT FORCE (.9072KG)/2LBS MIN.
- WAFER TO BE FLAT WITHIN (0.03MM/CM)/.003IN/IN
- THESE DIMENSIONS DEFINE THE MINIMUM COVERAGE FOR PLATING.
- THESE DIMENSIONS DEFINE THE MEASURING POINT FOR PLATING THICKNESS.
- FINISH (PER ES-88):
 - 90708-***1: GOLD PLATE (0.38um)/15uin MIN. IN SELECTED AREA. (TYPE 587) TIN PLATE (1.9um)/75uin MIN. IN SELECTED AREA. OVER (1.3um)/50uin MIN. NICKEL OVERALL.
 - 90708-***2: GOLD PLATE (0.76um)/30uin MIN. IN SELECTED AREA. (TYPE 599) TIN PLATE (1.9um)/75uin MIN. IN SELECTED AREA. OVER (1.3um)/50uin MIN. NICKEL OVERALL.
 - 90708-***3: GOLD PLATE (0.10um)/5uin MIN. IN SELECTED AREA. (TYPE 608) TIN PLATE (1.9um)/75uin MIN. IN SELECTED AREA. OVER (1.3um)/50uin MIN. NICKEL OVERALL.

8. RECOMMENDED PCB THICKNESS 1.6mm

| | | | | | | | | | | | | | |
|---|--|--------------------|---|--|--|-----------------|--|-------------------------------------|--------------|------------------------|--|--|--|
| <p>Note 8 Added EC NO: E2008-0068 DRWN: PGRADY CHKD: APPR: EOMAHONY</p> | <p>2007/08/24 2007/08/24 2007/08/24 2007/08/24</p> | <p>DESCRIPTION</p> | <p>QUALITY SYMBOLS</p> <p>▽=0 ◁=0</p> | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE | | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION | | | |
| | | | | | | MM/IN | | 2:1 | METRIC | | | | |
| | | | | | | | | DRAWN BY | | DATE | | TITLE | |
| | | | | | | | | CHECKED BY | | DATE | | <p>(2.54)/.100 PITCH DUAL ROW LOW PROFILE SHROUDED HEADER ASSEMBLY</p> | |
| | | | | APPROVED BY | | DATE | | <p>MOLEX MOLEX INCORPORATED</p> | | SHEET NO. | | | |
| | | | | MATERIAL NO. | | DOCUMENT NO. | | SDA-90708 | | 1 OF 1 | | | |
| | | | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SEE CHART | | | | | | | |
| | | | | | | SIZE | | | | | | | |
| | | | | | | A3 | | | | | | | |

9 8 7 6 5 4 3 2 1